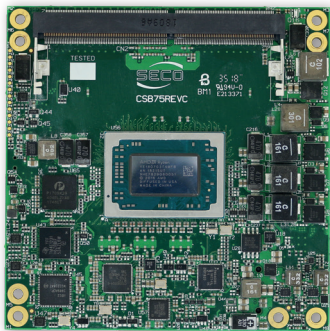




COMe-B75-CT6

COM Express® Compact 3.0 Type 6 Module with the AMD Ryzen™ Embedded V1000 processors

Next Generation x86 “Zen” Core and elite GPU performance



HIGHLIGHTS

| | |
|---|---|
| CPU AMD Ryzen™ Embedded V1000 processors | CONNECTIVITY 4x USB 3.0; 8x USB 2.0; 4x PCI-e x1 Gen 3, PEG x8 Gen3 |
| GRAPHICS AMD Radeon™ Vega GPU with up to 11 Compute Units DirectX® 12 supported | MEMORY Up to two DDR4 SO-DIMM Slots supporting DDR4-3200 ECC Memory |

Available in Industrial Temperature Range



MAIN FIELDS OF APPLICATION



Biomedical/
Medical devices



Digital Signage -
Infotainment



Gaming

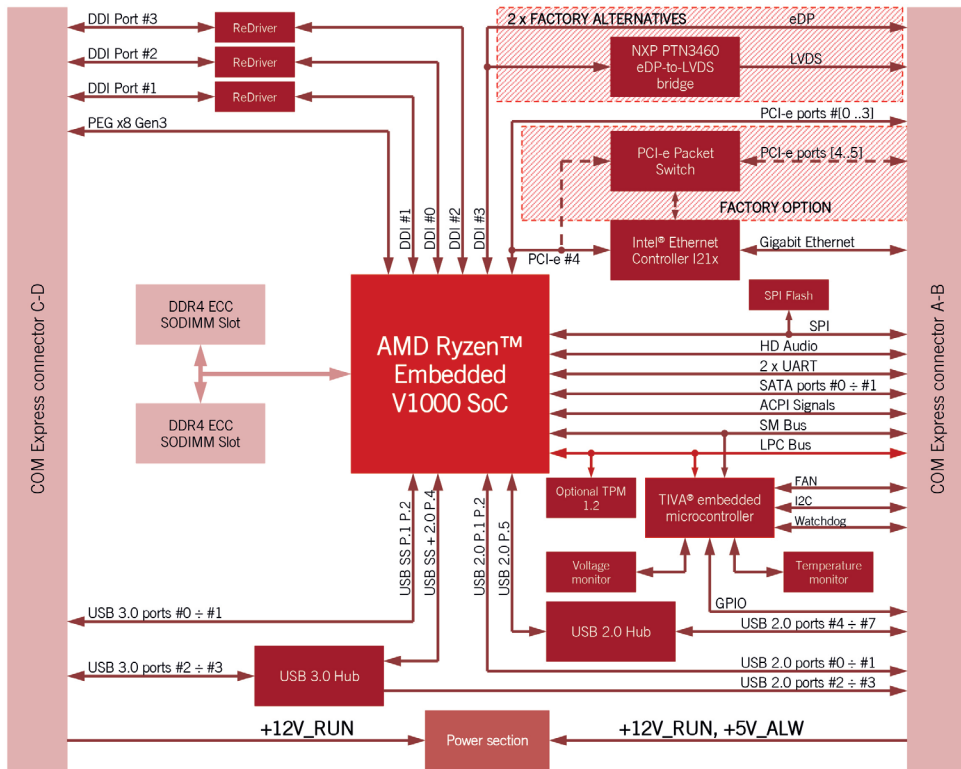
FEATURES

| | |
|--|--|
| Processor AMD Ryzen™ Embedded V1807B with AMD Radeon™ Vega 11 Graphics, Quad Core Dual Thread @ 3.35GHz (3.8 Boost), TDP 35-54W AMD Ryzen™ Embedded V1756B with AMD Radeon™ Vega 8 Graphics, Quad Core Dual Thread @ 3.25GHz (3.6 Boost), TDP 35-54W AMD Ryzen™ Embedded V1605B with AMD Radeon™ Vega 8 Graphics, Quad Core Dual Thread @ 2.0GHz (3.6 Boost), TDP 12-25W AMD Ryzen™ Embedded V1202B with AMD Radeon™ Vega 3 Graphics, Dual Core Dual Thread @ 2.3 GHz (3.2 Boost), TDP 12-25W AMD Ryzen™ Embedded V1404I with AMD Radeon™ Vega 3 Graphics, Quad Core / Single Thread, TDP 15W ,Industrial Temperature range | PCI-e Up to 4x PCI-e x1 Gen3 lanes + 2 x PCI-e x1 Gen2 ports PCI-express Graphics (PEG) x 8 Gen3 |
| Max Cores 4 | Audio HD Audio interface |
| Memory Up to two DDR4 SO-DIMM Slots supporting DDR4-3200 ECC and non- ECC Memory modules (DDR4-2400 with V1605B, V1202B and V1404I) Up to 16GB @ 3200Mhz, up to 32GB @ 2400MHz supported | Serial Ports 2 x UARTs |
| Graphics AMD Radeon™ Vega GPU with up to 11 Compute Units DirectX® 12 supported H.265 (10-bit) decode and 8-bit video encode VP9 decode 4 independent displays supported | Other Interfaces SPI, I2C bus, SM Bus, LPC bus, FAN management LID#/SLEEP#/PWRBTN#, Watchdog 4x GPI, 4 x GPO Optional TPM 1.2 module on-board |
| Video Interfaces 3 x Digital Display Interfaces (DDIs), supporting DP 1.3, DVI and HDMI 1.4/2.0 eDP or Single/Dual-Channel 18-/24- bit LVDS interface | Power Supply +12V _{DC} ± 10% and + 5V _{SB} (optional) |
| Video Resolution DDIs, eDP up to 4K LVDS up to 1920 x 1200 | Operating System Microsoft® Windows 10 Linux Ubuntu |
| Mass Storage 2 x S-ATA Gen3 Channels | Operating Temperature* 0°C ÷ +60°C (Commercial version) -40°C ÷ +85°C (Industrial version) |
| Networking Gigabit Ethernet interface Intel® I21x family GbE Controller | Dimensions 95 x 95 mm (COM Express™ Compact Form factor, Type 6 pinout) |
| USB 4 x USB 3.0 Host ports 8 x USB 2.0 Host ports | *Measured at any point of SECO standard heatspreader for this product, during any and all times (including start-up). Actual temperature will widely depend on application, enclosure and/or environment. Upon customer to consider application-specific cooling solutions for the final system to keep the heatspreader temperature in the range indicated. |

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BLOCK DIAGRAM



Information subject to change. Please visit www.seco.com to find the latest version of this datasheet.

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